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December 2013

# FPDB40PH60B PFC SPM<sup>®</sup> 3 Series for 2-Phase Bridgeless PFC

#### **Features**

- UL Certified No. E209204 (UL1557)
- 600 V 40 A 2-Phase Bridgeless PFC with Integral Gate Driver and Protection
- Very Low Thermal Resistance Using Al<sub>2</sub>O<sub>3</sub> DBC Substrate
- · Built-in NTC Thermistor for Temperature Monitoring
- · Built-in Shunt Resistor for Current Sensing
- · Optimized for 20kHz Switching Frequency
- · Isolation Rating: 2500 Vrms/min.

#### **Applications**

• 2-Phase Bridgeless PFC Converter

#### **Related Source**

• <u>AN-9041 - Bridgeless PFC SPM 3 Series Design</u> <u>Guide</u>

#### **General Description**

The FPDB40PH60B is an advanced PFC SPM® 3 module providing a fully-featured, high-performance Bridgeless PFC (Power Factor Correction) input power stage for consumer, medical, and industrial applications. These modules integrate optimized gate drive of the built-in IGBTs to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockout, over-current shutdown, thermal monitoring, and fault reporting. These modules also feature high-performance output diodes and shunt resistor for additional space savings and mounting convenience.

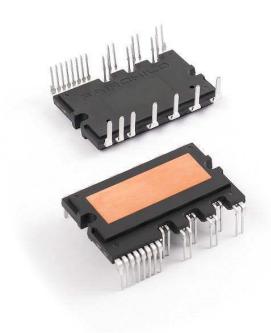


Figure 1. Package Overview

### Package Marking & Ordering Information

Device	Device Marking	Package	Packing Type	Quantity
FPDB40PH60B	FPDB40PH60B	SPMGC-027	Rail	10

### Integrated Drive, Protection and System Control Functions

- For IGBTs: gate drive circuit, Over-Current Protection (OCP), control supply circuit Under-Voltage Lock-Out (UVLO) Protection
- · Fault signal: corresponding to OC and UV fault
- · Built-in thermistor: temperature monitoring
- Input interface: active-HIGH interface, works with 3.3 / 5 V logic, Schmitt-trigger input

### **Pin Configuration**

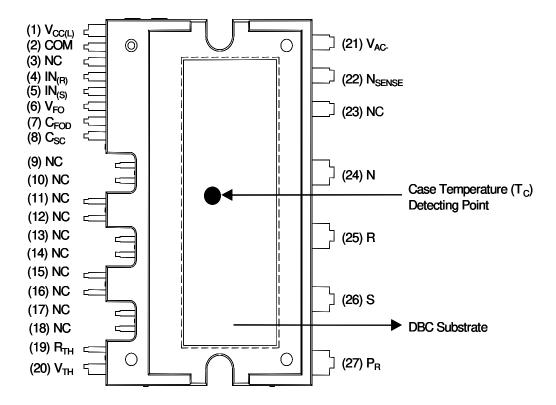


Figure 2. Top View

# **Pin Descriptions**

Pin Number	Pin Name	Pin Description	
1	V <sub>CC</sub>	Common Bias Voltage for IC and IGBTs Driving	
2	COM	Common Supply Ground	
4	IN <sub>(R)</sub>	Signal Input for Low-Side R-Phase IGBT	
5	IN <sub>(S)</sub>	Signal Input for Low-Side S-Phase IGBT	
6	V <sub>FO</sub>	Fault Output	
7	C <sub>FOD</sub>	OD Capacitor for Fault Output Duration Selection	
8	C <sub>SC</sub>	Capacitor(Low-Pass Filter) for Over-Current Detection	
19	R <sub>(TH)</sub>	Series Resistor for The Use of Thermistor	
20	V <sub>(TH)</sub>	Thermistor Bias Voltage	
21 V <sub>AC-</sub> Current Sensing Terminal		Current Sensing Terminal	
22 N <sub>SENSE</sub> Current Sensing Reference Terminal		Current Sensing Reference Terminal	
24	N	Negative Rail of DC-Link	
25	R	Output for R-Phase	
26	S	Output for S-Phase	
27	$P_{R}$	Positive Rail of DC-Link	
3, 9~18, 23	NC	No Connection	

## **Internal Equivalent Circuit**

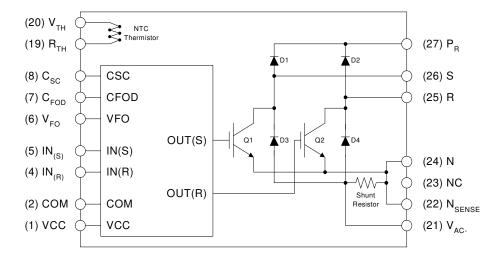


Figure 3. Internal Block Diagram

#### Notes:

1. Converter is composed of two IGBTs including four diodes and one IC which has gate driving and protection functions.

# **Absolute Maximum Ratings** ( $T_J = 25$ °C, unless otherwise specified.) **Converter Part**

Symbol	Item	Condition	Rating	Unit
V <sub>i</sub>	Supply Voltage	Applied between R - S	264	V <sub>rms</sub>
V <sub>i(Surge)</sub>	Supply Voltage (Surge)	Applied between R - S	500	V
V <sub>PN</sub>	Output Voltage	Applied between P - N	450	V
V <sub>PN(Surge)</sub>	Output Voltage (Surge)	Applied between P - N	500	V
V <sub>CES</sub>	Collector - Emitter Voltage		600	V
±Ι <sub>C</sub>	Each IGBT Collector Current	T <sub>C</sub> = 25°C	40	Α
±I <sub>CP</sub>	Each IGBT Collector Current (Peak)	T <sub>C</sub> = 25°C, Under 1 ms Pulse Width	70	Α
$P_{C}$	Collector Dissipation	T <sub>C</sub> = 25°C per IGBT	113	W
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage		600	V
I <sub>FSM</sub>	Peak Forward Surge Current	Single Half Sine-Wave	350	Α
P <sub>RSH</sub>	Power Rating of Shunt Resistor	T <sub>C</sub> < 125°C	2	W
TJ	Operating Junction Temperature	(Note 2)	-40 ~ 150	°C

#### Notes:

#### **Control Part**

Symbol	Item	Condition	Rating	Unit
V <sub>CC</sub>	Control Supply Voltage	Applied between V <sub>CC</sub> - COM	20	V
$V_{IN}$	Input Signal Voltage	Applied between IN - COM	-0.3 ~ 17.0	V
V <sub>FO</sub>	Fault Output Supply Voltage	Applied between V <sub>FO</sub> - COM	-0.3 ~ V <sub>CC</sub> +0.3	V
I <sub>FO</sub>	Fault Output Current	Sink Current at V <sub>FO</sub> Pin	5	mA
$V_{SC}$	Current Sensing Input Voltage	Applied between C <sub>SC</sub> - COM	-0.3~V <sub>CC</sub> +0.3	٧

### **Total System**

Symbol	Item	Condition	Rating	Unit
T <sub>C</sub>	Module Case Operation Temperature		-20 ~ 100	°C
T <sub>STG</sub>	Storage Temperature		-40 ~ 150	°C
V <sub>ISO</sub>	Isolation Voltage	60 Hz, Sinusoidal, AC 1 Minute, Connect Pins to Heat-Sink Plate	2500	V <sub>rms</sub>

#### **Thermal Resistance**

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
$R_{\theta(j-c)Q}$	Junction to Case Thermal Resistance	IGBT	-	-	1.1	°C/W
$R_{\theta(j\text{-}c)HD}$	(Referenced to PKG Center)	High-Side Diode	-	-	1.9	°C/W
$R_{\theta(j-c)LD}$		Low-Side Diode	-	-	1.4	°C/W

#### Notes:

<sup>2.</sup> The maximum junction temperature rating of the power chips integrated within the PFC SPM<sup>®</sup> product is  $150^{\circ}$ C(@T<sub>C</sub>  $\leq 100^{\circ}$ C).

<sup>3.</sup> For the measurement point of case temperature  $(T_C)$ , please refer to Figure 2.

# $\textbf{Electrical Characteristics} \ \, (\text{T}_{\text{J}} = 25^{\circ}\text{C}, \text{ unless otherwise specified.})$

#### **Converter Part**

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
V <sub>CE(SAT)</sub>	IGBT Saturation Voltage	V <sub>CC</sub> = 15 V, V <sub>IN</sub> = 5 V, I <sub>C</sub> = 40 A	-	1.8	2.3	V
$V_{FH}$	High-Side Diode Voltage	I <sub>F</sub> = 40 A	-	2.2	2.7	٧
$V_{FL}$	Low-Side Diode Voltage	I <sub>F</sub> = 40 A	-	1.15	1.55	<b>V</b>
t <sub>ON</sub>	Switching Times	V <sub>PN</sub> = 400 V, V <sub>CC</sub> = 15 V, I <sub>C</sub> = 40 A	-	500	-	ns
t <sub>C(ON)</sub>		$V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$ , Inductive Load	-	180	-	ns
t <sub>OFF</sub>		(Note 4)	-	500	1	ns
t <sub>C(OFF)</sub>			-	90	-	ns
t <sub>rr</sub>			-	43	-	ns
I <sub>rr</sub>			-	6	-	Α
R <sub>SENSE</sub>	Current-Sensing resistor		1.8	2.0	2.2	mΩ
I <sub>CES</sub>	Collector - Emitter Leakage Current	$V_{CE} = V_{CES}$	=	-	250	μА

Notes:
4. t<sub>ON</sub> and t<sub>OFF</sub> include the propagation delay of the internal drive IC. t<sub>C(ON)</sub> and t<sub>C(OFF)</sub> are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

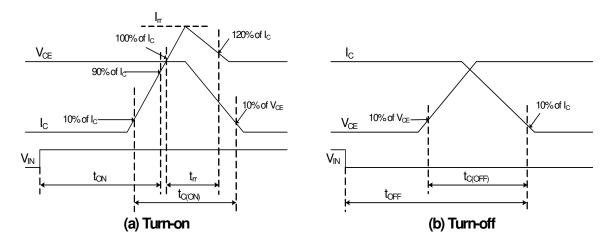


Figure 4. Switching Time Definition

#### **Control Part**

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
I <sub>QCCL</sub>	Quiescent V <sub>CC</sub> Supply Current	V <sub>CC</sub> = 15 V, IN = 0 V V <sub>CC</sub> - COM	-	-	26	mA
V <sub>FOH</sub>	Fault Output Voltage	$V_{SC}$ = 0 V, $V_{FO}$ Circuit: 4.7 k $\Omega$ to 5 V Pull-up	4.5	-	-	٧
V <sub>FOL</sub>		$V_{SC}$ = 1 V, $V_{FO}$ Circuit: 4.7 k $\Omega$ to 5 V Pull-up	-	-	0.8	٧
V <sub>SC(ref)</sub>	Over-Current Trip Level	V <sub>CC</sub> = 15 V		0.50	0.55	٧
UV <sub>CCD</sub>	Supply Circuit Under-Voltage	Detection Level	10.7	11.9	13.0	V
UV <sub>CCR</sub>	Protection	Reset Level	11.2	12.4	13.2	٧
t <sub>FOD</sub>	Fault-Out Pulse Width	C <sub>FOD</sub> = 33 nF (Note 5)	1.4	1.8	2.0	ms
V <sub>IN(ON)</sub>	ON Threshold Voltage	Applied between IN - COM	3.0	-	-	٧
V <sub>IN(OFF)</sub>	OFF Threshold Voltage		-	-	0.8	٧
R <sub>TH</sub>	Resistance of Thermistor	at T <sub>C</sub> = 25°C (See Figure 5)	-	50	-	kΩ
		at T <sub>C</sub> = 80°C (See Figure 5)	-	5.76	-	kΩ

Notes:
5. The fault-out pulse width  $t_{FOD}$  depends on the capacitance value of  $C_{FOD}$  according to the following approximate equation:  $C_{FOD} = 18.3 \times 10^{-6} \times t_{FOD}[F]$ 



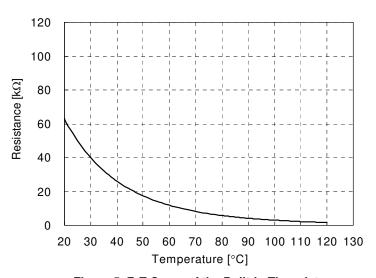


Figure 5. R-T Curve of the Built-in Thermistor

## **Recommended Operating conditions**

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
V <sub>I</sub>	Input Supply Voltage	Applied between R - S	180	-	264	V <sub>rms</sub>
V <sub>PN</sub>	Output Voltage	Applied between P - N	-	280	400	٧
V <sub>CC</sub>	Control Supply Voltage	Applied between V <sub>CC</sub> - COM	13.5	15	16.5	٧
dV <sub>CC</sub> /dt	Control Supply Variation	Applied between IN - COM	-1	-	1	V/µs
f <sub>PWM</sub>	PWM Input Signal	$T_C \le 100$ °C, $T_J \le 125$ °C, per IGBT	-	20	-	kHz

# **Mechanical Characteristics and Ratings**

Item	Co	ndition	Min.	Тур.	Max.	Units
Mounting Torque	Mounting Screw: M3	Recommended 0.62 N•m	0.51	0.62	0.72	N•m
Device Flatness	See Figure 6		0	-	+120	μm
Weight			-	15.00	-	g

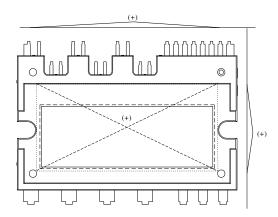
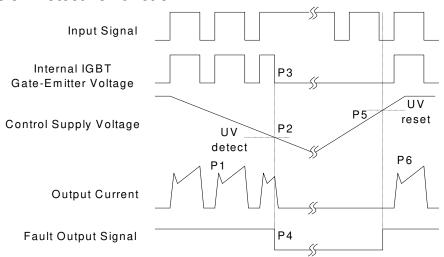


Figure 6. Flatness Measurement Position

#### **Time Charts of Protective Function**

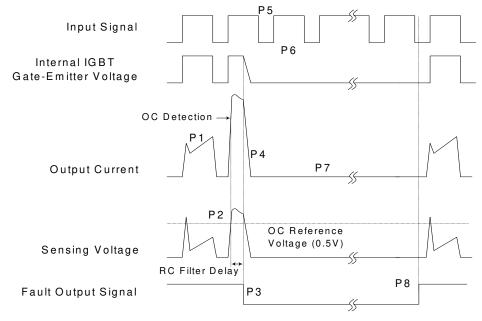


P1: Normal operation: IGBT ON and conducting current.

P2: Under-voltage detection.
P3: IGBT gate interrupt.
P4: Fault signal generation.
P5: Under-voltage reset.

P6: Normal operation: IGBT ON and conducting current.

Figure 7. Under-Voltage Protection



P1: Normal operation: IGBT ON and conducting current.

P2 : Over current detection.

P3: IGBT gate interrupt / fault signal generation.

P4: IGBT is slowly turned off.

P5: IGBT OFF signal.

P6 : IGBT ON signal: but IGBT cannot be turned on during the fault output activation.

P7: IGBT OFF state.

P8 : Fault output reset and normal operation start.

**Figure 8. Over-Current Protection** 

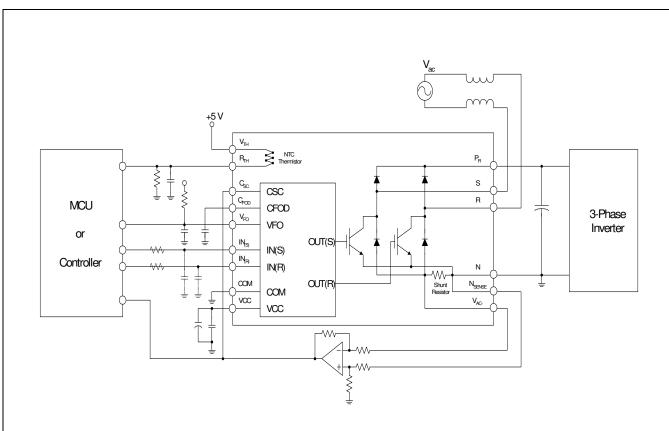


Figure 9. Application Example

Notes: 6. For the over-current protection, please set time constant in the range  $~3\sim 4~\mu s.$ 

#### **Detailed Package Outline Drawings** (0.136)(0.30)0.60 20X (0.70) 2X LEAD PITCH (TOLERANCE: ±0.30) A: 1.778 (2.31)(1.55)B: 2.050 C: 2.531 8.20 7.60 (13.20)ø3.40 2x (R0.70) 17,644 13.335 0.136 (2.76) 2X 4,445 20.447 00 0 ¢ 00000000 DETAIL A 11.68 (0.70) 2X 31.56 7.92 4X 7.32 4X NOTES: UNLESS OTHERWISE SPECIFIED A) THIS PACKAGE DOES NOT COMPLY DETAIL B TO ANY CURRENT PACKAGING STANDARD 11.62 11.24 B) ALL DIMENSIONS ARE IN MILLIMETERS 19.24 15.24 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, 19.24 MOLD FLASH, AND TIE BAR EXTRUSIONS

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